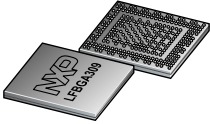


SOT2128-1

LFBGA309, low profile fine-pitched ball grid array package, 309 terminals, 0.5 mm pitch, molded array, 10.6 mm x 11.3 mm x 1.13 mm body

28 June 2023

Package information



1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	LFBGA309
Package style descriptive code	LFBGA (low profile fine-pitch ball grid array)
Mounting method type	S (surface mount)
Issue date	21-06-2023
Manufacturer package code	98ASA01727D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	10.45	10.6	10.75	mm
package width	11.15	11.3	11.45	mm
package height	-	1.13	1.23	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	309	-	



LFBGA309, low profile fine-pitched ball grid array package, 309 terminals, 0.5 mm pitch, molded array, 10.6 mm x 11.3 mm body

2 Package outline

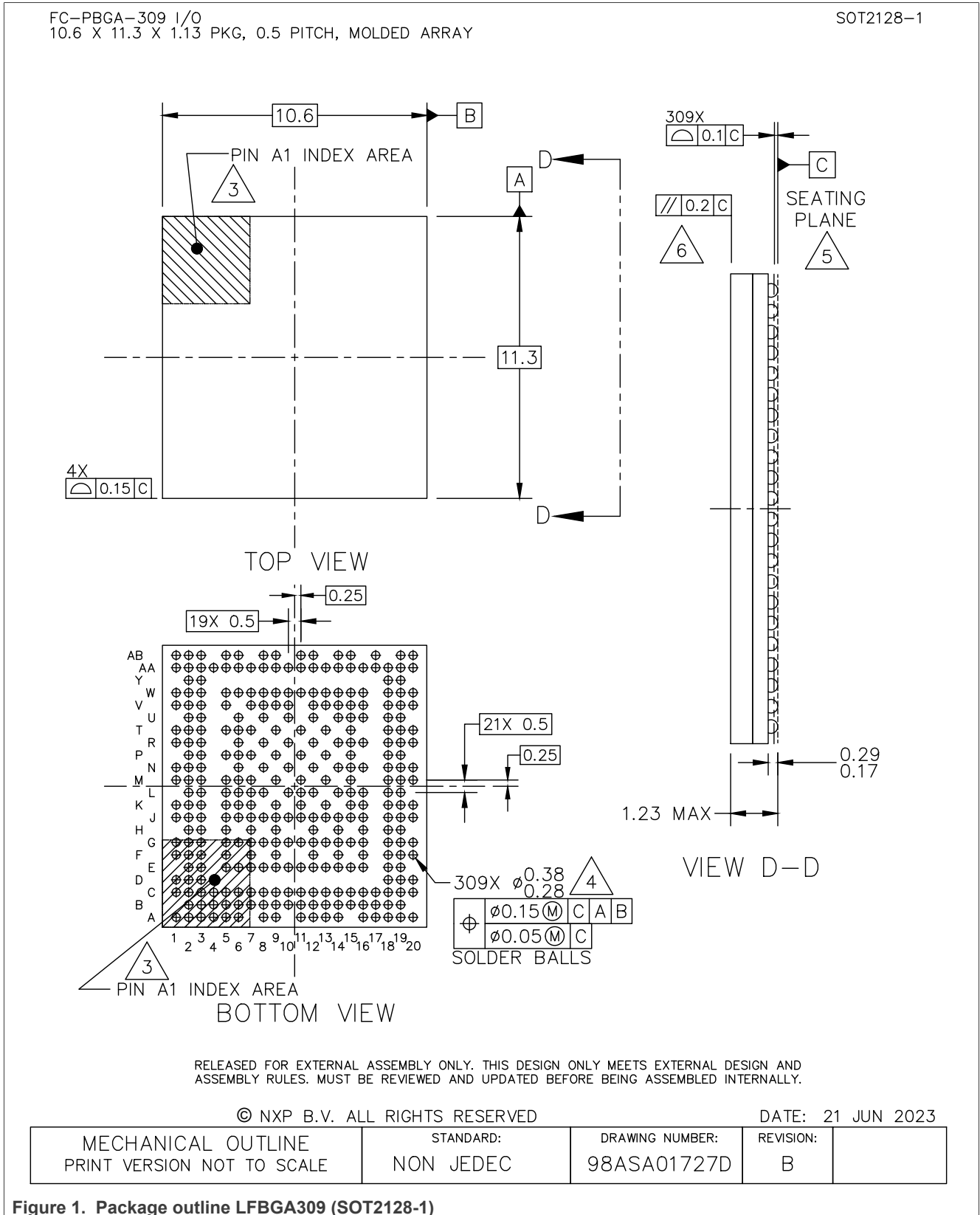


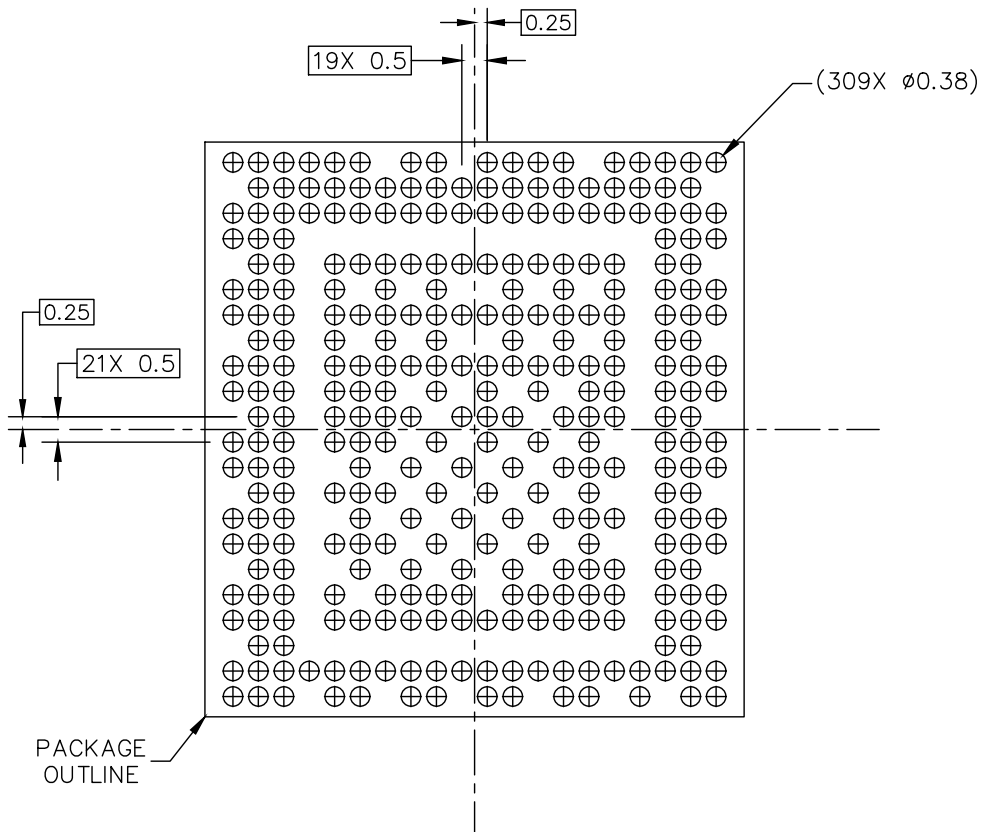
Figure 1. Package outline LFBGA309 (SOT2128-1)

LFBGA309, low profile fine-pitched ball grid array package, 309 terminals, 0.5 mm pitch, molded array, 10.6 mm x 11.3 mm x 1.13 mm body

3 Soldering

FC-PBGA-309 I/O
10.6 X 11.3 X 1.13 PKG, 0.5 PITCH, MOLDED ARRAY

SOT2128-1



PCB DESIGN GUIDELINES – SOLDER MASK OPENING PATTERN

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DATE: 21 JUN 2023

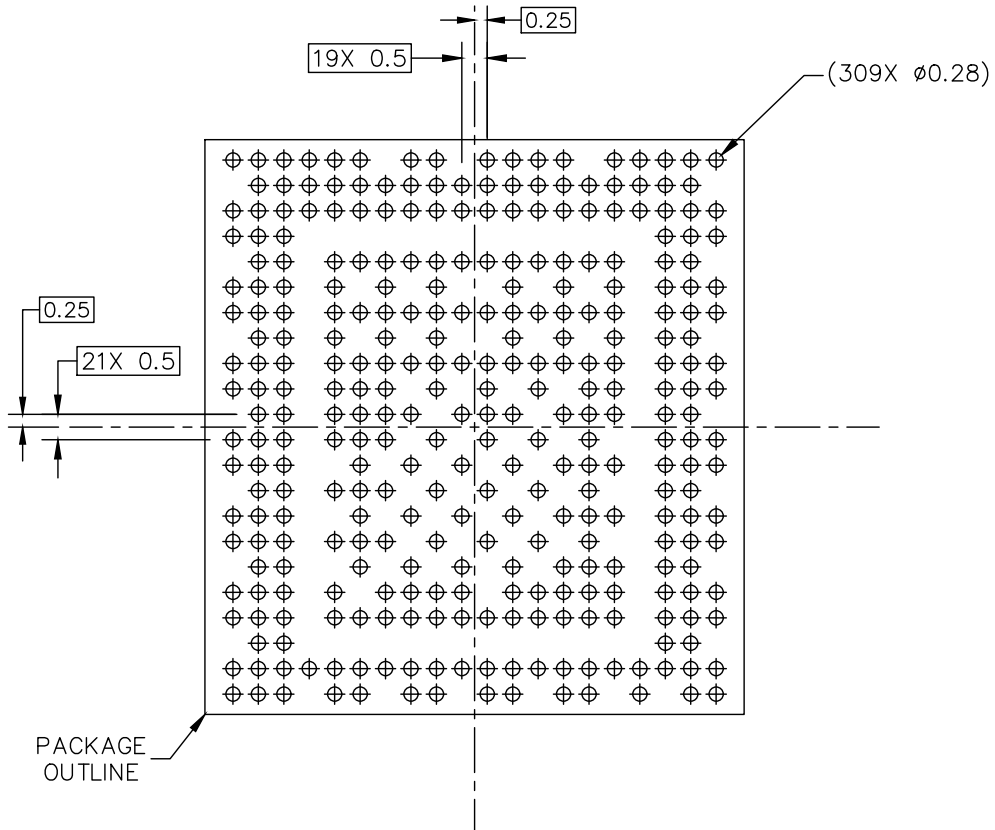
MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01727D	REVISION: B	
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Figure 2. Reflow soldering footprint part1 for LFBGA309 (SOT2128-1)

LFBGA309, low profile fine-pitched ball grid array package, 309 terminals, 0.5 mm pitch, molded array, 10.6 mm x 11.3 mm x 1.13 mm body

FC-PBGA-309 I/O
10.6 X 11.3 X 1.13 PKG, 0.5 PITCH, MOLDED ARRAY

SOT2128-1



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

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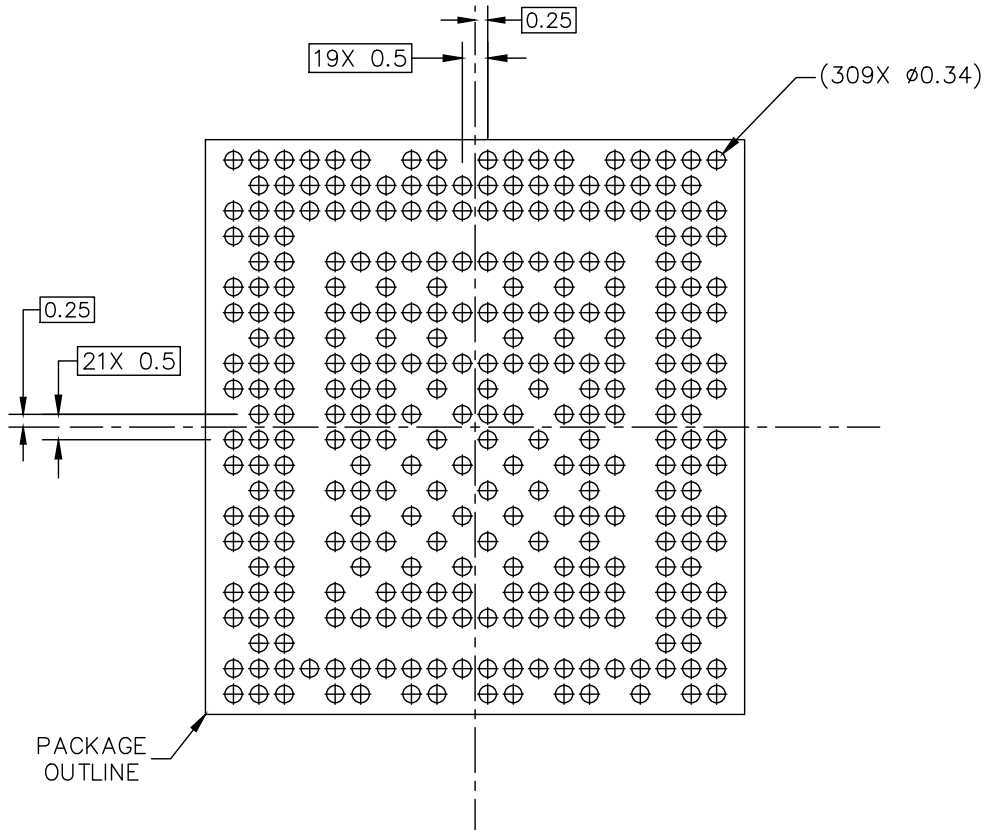
MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01727D	REVISION: B	
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Figure 3. Reflow soldering footprint part2 for LFBGA309 (SOT2128-1)

LFBGA309, low profile fine-pitched ball grid array package, 309 terminals, 0.5 mm pitch, molded array, 10.6 mm x 11.3 mm x 1.13 mm body

FC-PBGA-309 I/O
10.6 X 11.3 X 1.13 PKG, 0.5 PITCH, MOLDED ARRAY

SOT2128-1



RECOMMENDED STENCIL THICKNESS 0.125 MM

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01727D	REVISION: B	
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Figure 4. Reflow soldering footprint part3 for LFBGA309 (SOT2128-1)

LFBGA309, low profile fine-pitched ball grid array package, 309 terminals, 0.5 mm pitch, molded array, 10.6 mm x 11.3 mm x 1.13 mm body

FC-PBGA-309 I/O
10.6 X 11.3 X 1.13 PKG, 0.5 PITCH, MOLDED ARRAY

SOT2128-1

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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DATE: 21 JUN 2023

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01727D	REVISION: B	
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Figure 5. Package outline note LFBGA309 (SOT2128-1)

LFBGA309, low profile fine-pitched ball grid array package, 309 terminals, 0.5 mm pitch, molded array, 10.6 mm x 11.3 mm x 1.13 mm body

4 Legal information

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LFBGA309, low profile fine-pitched ball grid array package, 309 terminals, 0.5 mm pitch, molded array, 10.6 mm x 11.3 mm x 1.13 mm body

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